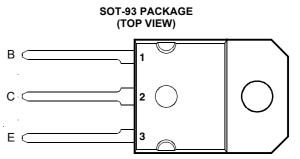
JULY 1968 - REVISED MARCH 1997

- Designed for Complementary Use with the TIP33 Series
- 80 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- 15 A Peak Collector Current
- Customer-Specified Selections Available



Pin 2 is in electrical contact with the mounting base.

MDTRAA

### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	TIP34		-80	
Collector base voltage $(I - 0)$	TIP34A	V	-100	v
Collector-base voltage ( $I_E = 0$ )	TIP34B	V <sub>CBO</sub>	-120	v
	TIP34C		-140	
	TIP34		-40	
Collector emitter veltage (I 0)	TIP34A	V	-60	v
Collector-emitter voltage $(I_B = 0)$	TIP34B	V <sub>CEO</sub>	-80	v
	TIP34C		-100	
Emitter-base voltage	V <sub>EBO</sub>	-5	V	
Continuous collector current			-10	A
Peak collector current (see Note 1)			-15	A
Continuous base current			-3	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			80	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			3.5	W
Unclamped inductive load energy (see Note 4)			62.5	mJ
Operating junction temperature range			-65 to +150	°C
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C	
Lead temperature 3.2 mm from case for 10 seconds	TL	250	°C	

NOTES: 1. This value applies for  $t_p \leq 0.3$  ms, duty cycle  $\leq 10\%.$ 

2. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.

3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.

4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH,  $I_{B(on)}$  = -0.4 A,  $R_{BE}$  = 100  $\Omega$ ,  $V_{BE(off)}$  = 0,  $R_S$  = 0.1  $\Omega$ ,  $V_{CC}$  = -20 V.



JULY 1968 - REVISED MARCH 1997

### electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	ТҮР	MAX	UNIT
V <sub>(BR)CEO</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = -30 mA (see Note 5)		TIP34	-40			
			I <sub>B</sub> = 0	TIP34A	-60			v
				TIP34B	-80			v
				TIP34C	-100			
		V <sub>CE</sub> = -80 V	$V_{BE} = 0$	TIP34			-0.4	
	Collector-emitter	V <sub>CE</sub> = -100 V	V <sub>BE</sub> = 0 V <sub>BE</sub> = 0	TIP34A TIP34B			-0.4	mA
ICES	cut-off current	V <sub>CE</sub> = -120 V					-0.4	ШA
		V <sub>CE</sub> = -140 V	$V_{BE} = 0$	TIP34C			-0.4	
1	Collector cut-off	V <sub>CE</sub> = -30 V	I <sub>B</sub> = 0	TIP34/34A			-0.7	mA
ICEO	current	V <sub>CE</sub> = -60 V	$I_B = 0$	TIP34B/34C			-0.7	ШA
I	Emitter cut-off	V <sub>EB</sub> = -5 V	$I_{\rm C} = 0$				-1	mA
I <sub>EBO</sub>	current	VEB5 V	1 <u>C</u> = 0				- 1	
h <sub>FE</sub>	Forward current	$V_{CE} = -4 V$	I <sub>C</sub> = -1 A	(see Notes 5 and 6)	40			
"FE	transfer ratio	V <sub>CE</sub> = -4 V	I <sub>C</sub> = -3 A		20		100	
Varue	Collector-emitter	I <sub>B</sub> = -0.3 A	I <sub>C</sub> = -3 A	(see Notes 5 and 6)			-1	v
V <sub>CE(sat)</sub>	saturation voltage	I <sub>B</sub> = -2.5 A	I <sub>C</sub> = -10 A				-4	v
V	Base-emitter	$V_{CE} = -4 V$	I <sub>C</sub> = -3 A	(see Notes 5 and 6)			-1.6	v
$V_{BE}$	voltage	$V_{CE} = -4 V$	I <sub>C</sub> = -10 A				-3	v
h <sub>fe</sub>	Small signal forward	V <sub>CE</sub> = -10 V	I <sub>C</sub> = -0.5 A	f = 1 kHz	20			
	current transfer ratio	VCE - 10 V	IC = -0.5 A		20			
h <sub>fe</sub>	Small signal forward	V <sub>CE</sub> = -10 V	I <sub>C</sub> = -0.5 A f = 1 MHz	f – 1 MHz	3			
l' fel	current transfer ratio	VCE - 10 V		5				

NOTES: 5. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu s,$  duty cycle  $\leq$  2%.

6. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

### thermal characteristics

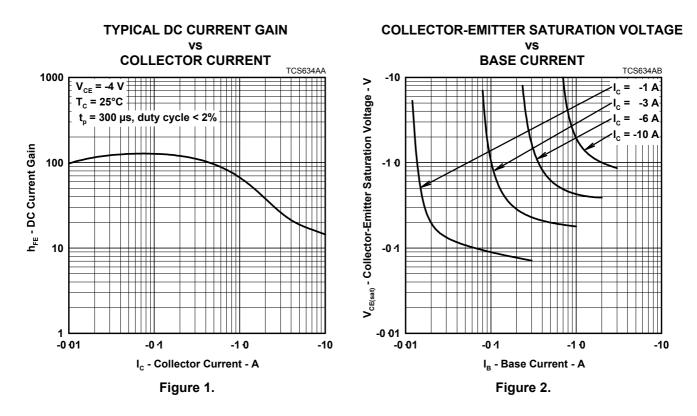
PARAMETER			ТҮР	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.56	°C/W
$R_{\thetaJA}$	Junction to free air thermal resistance			35.7	°C/W

### resistive-load-switching characteristics at 25°C case temperature

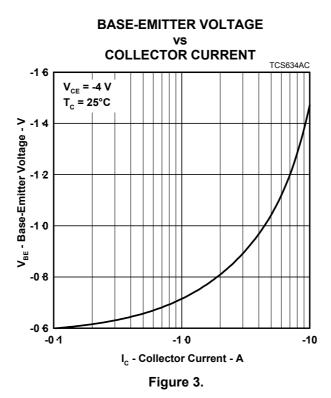
	PARAMETER	TEST CONDITIONS <sup>†</sup>			MIN	ТҮР	MAX	UNIT
t <sub>or</sub>	n Turn-on time	I <sub>C</sub> = -6 A	I <sub>B(on)</sub> = -0.6 A	$I_{B(off)} = 0.6 A$		0.4		μs
t <sub>of</sub>	<sub>f</sub> Turn-off time	$V_{BE(off)} = 4 V$	$R_L = 5 \Omega$	$t_p$ = 20 µs, dc $\leq$ 2%		0.7		μs

<sup>†</sup> Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

JULY 1968 - REVISED MARCH 1997

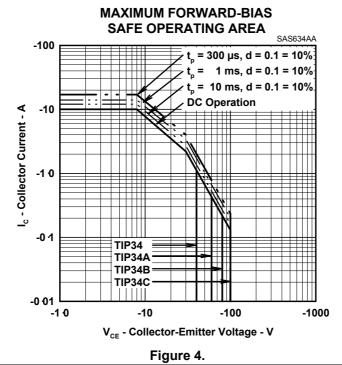


### **TYPICAL CHARACTERISTICS**



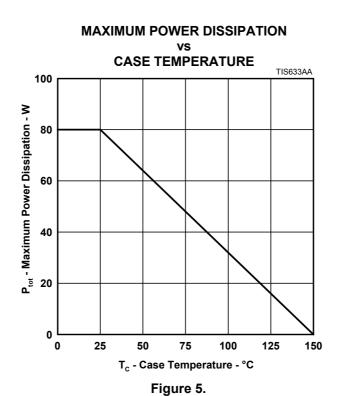
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### MAXIMUM SAFE OPERATING REGIONS





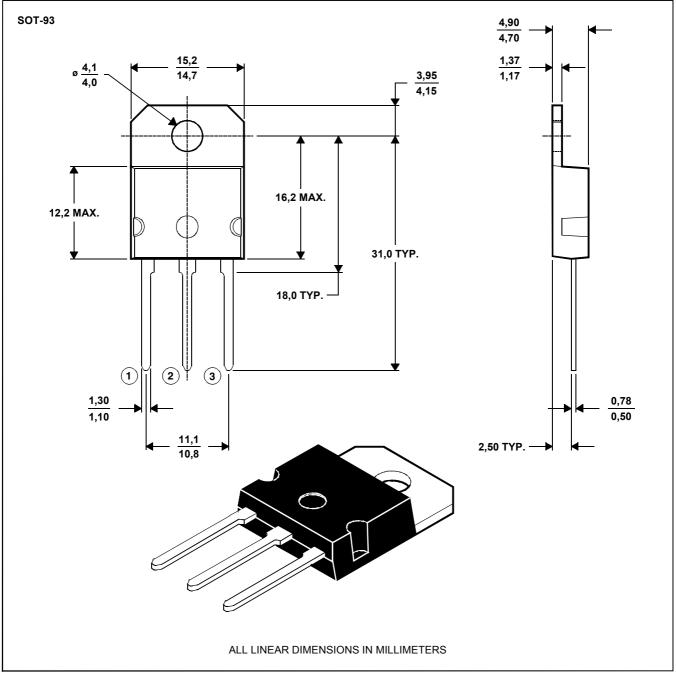
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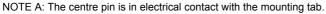
### **MECHANICAL DATA**

### SOT-93

#### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.





MDXXAW



JULY 1968 - REVISED MARCH 1997

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